

IEEE 802 Nov 2023

**IEEE 802.3 Ethernet WG
Closing Plenary
16 Nov 2023**

**IEEE P802.3dj
200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s
Ethernet Task Force
Closing Report**



IEEE P802.3dj Task Force Project information

- **Organization**
 - **John D'Ambrosia, Chair, IEEE P802.3dj Task Force**
 - **Mark Nowell, Vice-Chair, IEEE P802.3dj Task Force; Chair, Optics Track**
 - **Kent Lusted, Secretary, Chair, Electrical Track**
 - **Matt Brown, IEEE P802.3dj Chief Editor**
 - **Gary Nicholl, Chair, Architecture and Logic Track**
- **Task force web and reflector information:**
 - Home page: <https://www.ieee802.org/3/df/index.html>
 - Reflector Info - <https://www.ieee802.org/3/df/reflector.html>
 - TF Reflector: stds-802-3-b400g@listserv.ieee.org
 - Logic Reflector: stds-802-3-b400g-logic@listserv.ieee.org
 - Optical Reflector: stds-802-3-b400g-optx@listserv.ieee.org
 - Electrical Reflector: stds-802-3-b400g-elec@listserv.ieee.org
- **Project Documentation –**
 - **PAR :** https://www.ieee802.org/3/dj/projdoc/P802d3dj_PAR.pdf
 - **CSD:** <https://mentor.ieee.org/802-ec/dcn/22/ec-22-0256-00-ACSD-p802-3dj.pdf>
 - **Objectives:** https://www.ieee802.org/3/dj/projdoc/objectives_P802d3dj_230518.pdf
 - **Adopted Timeline:** https://www.ieee802.org/3/dj/projdoc/timeline_3dj_230116.pdf
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Activities This Week

- **Heard 31 technical presentations**
 - https://www.ieee802.org/3/dj/public/23_11/index.html
 - **Additional presentations will be heard at Nov 28&29 Contingent interim meeting**
- **Significant Progress made!!!! - Key Decisions (see next slide) in all areas (Architectural, Copper, Optical) were made!**
- **Discussed project time line status – update decision pending**
- **Generated liaison to ITU-T regarding G.652 fiber link property**

Decisions

Decisions noted in **GREEN** approved via **UNANIMOUS CONSENT**

Logic

- filled in some holes found in the previously adopted logic baselines
- adopted "FECo" as the only FEC for the 500m SMF PMDs (200GBASE-DR1, 400GBASE-DR2, 800GBASE-DR4, 1.6TBASE-DR8)

Optical

- Adopted an additional 800 GbE optical objective (4 wavelength, 500m)
- Adopted a majority of the optical PMD baselines:
 - 200GBASE-DR1, 400GBASE-DR2, 800GBASE-DR4, 1.6TBASE-DR8
 - 200GBASE-FR1-2, 400GBASE-DR2-2, 800GBASE-DR4-2, 1.6TBASE-DR8-2
 - 800GBASE-FR4
 - 800GBASE-LR4 (802.3 y/n/a: 78 / 1 / 14)

Electrical

- Adopt a two package approach for electrical KR and C2C AUI
- Adopted key package parameters or backplane and CR objectives
- Adopted host and cable assembly insertion loss budgets
- Adopted DER_0 and both host and cable assembly insertion loss budgets for CR objectives
- Adopted the "TP1-TP4 IL" column in the table and MCB insertion loss

Proposed Modified IEEE P802.3dj Objectives

Adopted IEEE P802.3dj Objectives (1 of 2)

- **Non-Rate Specific**
 - Support full-duplex operation only
 - Preserve the Ethernet frame format utilizing the Ethernet MAC
 - Preserve minimum and maximum FrameSize of current IEEE 802.3 standard
 - Support a BER of better than or equal to 10^{-13} at the MAC/PLS service interface (or the frame loss ratio equivalent)
 - Provide support to enable mapping over OTN
- **200 Gb/s Related**
 - Support a MAC data rate of 200 Gb/s
 - Support optional single-lane 200 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
 - Define a physical layer specification that supports 200 Gb/s operation:
 - over 1 lane over electrical backplanes supporting a die-to-die insertion loss ≤ 40 dB at 53.125 GHz **
 - over 1 pair of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter
 - over 1 pair of SMF with lengths up to at least 500 m
 - over 1 pair of SMF with lengths up to at least 2 km
- **400 Gb/s Related**
 - Support a MAC data rate of 400 Gb/s
 - Support optional two-lane 400 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
 - Define a physical layer specification that supports 400 Gb/s operation:
 - over 2 lanes over electrical backplanes supporting a die-to-die insertion loss ≤ 40 dB at 53.125 GHz **
 - over 2 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter
 - over 2 pairs of SMF with lengths up to at least 500 m
 - over 2 pairs of SMF with lengths up to at least 2 km

Adopted IEEE P802.3dj Objectives (2 of 2)

• 800 Gb/s Related

- Support a MAC data rate of 800 Gb/s
- Support optional four-lane 800 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
- Define a physical layer specification that supports 800 Gb/s operation:
 - over 4 lanes over electrical backplanes supporting a die-to-die insertion loss ≤ 40 dB at 53.125 GHz **
 - over 4 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter
 - over 4 pairs of SMF with lengths up to at least 500 m
 - over 4 pairs of SMF with lengths up to at least 2 km
 - **over 4 wavelengths over a single SMF in each direction with lengths up to at least 500 m *****
 - over 4 wavelengths over a single SMF in each direction with lengths up to at least 2 km
 - over 1 wavelength over a single SMF in each direction with lengths up to at least 10 km *
 - over 4 wavelengths over a single SMF in each direction with lengths up to at least 10 km *
 - over a single SMF in each direction with lengths up to at least 40 km

• 1.6 Tb/s Related

- Support a MAC data rate of 1.6 Tb/s
- Support optional sixteen-lane 1.6 Tb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
- Support optional eight-lane 1.6 Tb/s attachment unit interfaces for chip-to-module and chip-to-chip applications
- Define a physical layer specification that supports 1.6 Tb/s operation:
 - over 8 lanes over electrical backplanes supporting a die-to-die insertion loss ≤ 40 dB at 53.125 GHz **
 - over 8 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter
 - over 8 pairs of SMF with lengths up to at least 500 m
 - over 8 pairs of SMF with lengths up to at least 2 km

* - Approved by IEEE 802.3 WG 16 Mar 2023

** - Approved by IEEE 802.3 WG 18 May 2023

*** - Pending IEEE 802.3 WG Approval, 16 Nov 2023

WG Motion

Motion	Move that the IEEE 802.3 Working Group approve the IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force objectives, as per 1123_3dj_close_report.pdf
Technical (>= 75%)	
Moved by	Kent Lusted
Second by	Mark Nowell
Results 802.3 (y/n/a)	

WG Motion

Motion	Move that the IEEE 802.3 Working Group approve: <ul style="list-style-type: none">IEEE_802d3_to_ITU_3dj_1123_Redacted.pdf with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to ITU-T SG15.
Technical (>= 75%)	
Moved by	John D'Ambrosia
Second by	Mark Nowell
Results 802.3 (y/n/a)	

Summary IEEE P802.3dj Progress @ End of 16 Nov 2023 Meeting – Logic

	AUI	Backplane	CU Cable	SMF 500m/2km	SMF 10km 4 Wavelength	SMF 10km 1 Wavelength	SMF 40km
Ethernet Rate	PCS/FEC/PMA?	PCS/FEC/PMA?	PCS/FEC/PMA?	PCS/FEC/PMA?	PCS/FEC/PMA?	PCS/FEC/PMA?	PCS/FEC/PMA?
200 Gb/s	Adopted	Adopted	Adopted	Adopted	Proposed	Proposed	Proposed
400 Gb/s	Adopted	Adopted	Adopted	Adopted	Proposed	Proposed	Proposed
800 Gb/s	Adopted	Adopted	Adopted	Adopted	Adopted	Adopted	Two proposals
1.6 Tb/s	Adopted	Adopted	Adopted	Adopted	Proposed	Proposed	Proposed

Adopted baselines

Proposed Baselines

Summary IEEE P802.3dj Progress @ End of 16 Nov 2023 Meeting – PMDs (& AUIs)

Ethernet Rate	Assumed Signaling Rate	AUI	Backplane	Cu Cable	SMF 500m	SMF 2km	SMF 10km	SMF 40km
200 Gb/s	200 Gb/s	200GAUI-1 C2C C2M	200GBASE-KR1	200GBASE-CR1	200GBASE-DR1	200GBASE-FR1		
400 Gb/s	200 Gb/s	400GAUI-2 C2C C2M	400GBASE-KR2	400GBASE-CR2	400GBASE-DR2	400GBASE-DR2-2		
800 Gb/s	200 Gb/s	800GAUI-4 C2C C2M	800GBASE-KR4	800GBASE-CR4	1. 800GBASE-DR4 2. 800GBASE over 4λ	1. 800GBASE-DR4-2 2. 800GBASE-FR4	800GBASE-LR4	
	800 Gb/s						Over single SMF in each direction Coherent	Over single SMF in each direction Coherent
1.6 Tb/s	100 Gb/s	1.6TAUI-16 C2C C2M						
	200 Gb/s	1.6TAUI-8 C2C C2M	1.6TBASE-KR8	1.6TBASE-CR8	1.6TBASE-DR8	1.6TBASE-DR8-2		

Adopted baselines

Proposed Baselines

Future Meetings

IEEE P802.3cw: <https://www.ieee802.org/3/cw/public/index.html>

IEEE P802.3df: <https://www.ieee802.org/3/df/public/index.html>

IEEE P802.3dj: <https://www.ieee802.org/3/dj/public/index.html>

- Any additional meetings will be announced, as appropriate.
- IEEE P802.3cw
 - Contingent Electronic Meeting – 11 Dec 2023, 9am to 1pm
 - Contingent Electronic Meeting – 08 Jan 2024, 9am to 1pm
- IEEE P802.3df
 - Contingent Electronic Meeting – 18 Dec 2023, 9am to 1pm
 - Contingent Electronic Meeting – 09 - 11 Jan 2024, 9am to 1pm
- IEEE P802.3dj
 - Contingent Electronic Meeting – 28 – 29 Nov 2023, 9am to 1pm
 - Electrical & Logic/Optical Meetings – TBA
- Joint IEEE P802.3cw / df / dj Task Force Meeting
 - Week of 22 – 25 Jan 2024

THANK YOU!

